MT53E256M32D2DS-053 AUT

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Specs

Orderable Parts for: MT53E256M32D2DS-053 AUT

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	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT53E256M32D2DS-053 AUT:B	**Production**	N/A	D9WQZ	N/A	N/A	No		N/A

Detailed Specifications

Technology	LPDDR4	**Density**	8Gb	**Part Status**	Production	**RoHS**	Yes
Depth	256Mb	**Width**	x32	**Voltage**	1.1V/0.6V	**Package**	WFBGA
Pin Count	200-ball	**Clock Rate**	1866 MHz	**Data Rate**	DDR4-3732	**Cycle Time**	
Op. Temp.	-40C to +125C	**Brand**	Micron				

RoHS Certificates

RoHS Certificates

RoHS Certificate of Compliance (PDF)

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2011/65/EU and 2015/863/EU, a.k.a. Restriction of Hazardous Substances (RoHS) Directive (Recast) without exemptions.

File Type: (PDF) **Updated:** 09/2018

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RoHS Certificates

China RoHS Certificate (PDF)

Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

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Documentation & Support

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Technical Notes

SEARCH (9) LPDRAM TECHNICAL NOTES

Technical Notes

Technical Note: Low-Power Function of Mobile RAM - Deep Power Down (DPD) (PDF)

DRAM
LPDRAM

(E0598E21) This technical note describes Deep Power Down (DPD), one of the low-power functions that have been adapted to Mobile DRAM.

File Type: PDF **Updated:** 02/26/2014

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Technical Notes

Technical Note: Low-Power Function of Mobile RAM - Partial Array Self Refresh (PASR) (PDF)

DRAM
LPDRAM

(E0597E10) This technical note describes Partial Array Self Refresh (PASR), one of the low-power functions that have been adapted to Mobile DRAM.

File Type: PDF **Updated:** 02/26/2014

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Customer Service Notes

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Customer Service Note

Product Marks, Product Labels, and Packaging Labels (PDF)

3D XPoint
Client
Cloud
Cloud
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(CSN-11) The first section of this customer service note describes the product marks and labels we place on our devices. The second section describes the labels used on and in our packaging.

File Type: PDF **Updated:** 08/24/2018 DOWNLOAD

Customer Service Note

Micron BGA Manufacturer's User Guide (PDF)

DDR2 SDRAM
DDR4 SDRAM
Embedded USB
eMMC
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(CSN-33) Provides information to enable customers to easily integrate both leading-edge and legacy Micron's ball grid array (BGA) packages into their manufacturing processes. It is intended as a set of high-level guidelines and a reference manual describing typical package-related and...

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